

Table 1

Others : See Table 1

Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics		Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A220Q55B DSS1NB32A220Q91A DSS1NB32A220Q92A DSS1NB32A220Q93A	22 pF±10%				
	DSS1NB32A330Q55B DSS1NB32A330Q91A DSS1NB32A330Q92A DSS1NB32A330Q93A	33 pF±10%	±10%	100VDC	250VDC	0.45g
	DSS1NB32A470Q55B DSS1NB32A470Q91A DSS1NB32A470Q92A DSS1NB32A470Q93A	47 pF±10%				

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Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics	Rated Voltage	Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A680Q55B DSS1NB32A680Q91A DSS1NB32A680Q92A DSS1NB32A680Q93A	68 pF±10%				
	DSS1NB32A101Q55B DSS1NB32A101Q91A DSS1NB32A101Q92A DSS1NB32A101Q93A	100 pF±10%	-			
	DSS1NB32A121Q55B DSS1NB32A121Q91A DSS1NB32A121Q92A	120 pF±10%	-		250VDC	0.45g
	DSS1NB32A121Q93A DSS1NB32A151Q55B DSS1NB32A151Q91A DSS1NB32A151Q92A	150 pF±10%				
	DSS1NB32A151Q93A DSS1NB32A221Q55B DSS1NB32A221Q91A DSS1NB32A221Q92A	220 pF±10%				
	DSS1NB32A221Q93A DSS1NB32A271Q55B DSS1NB32A271Q91A DSS1NB32A271Q92A	270 pF±10%				
	DSS1NB32A271Q93A DSS1NB32A331Q55B DSS1NB32A331Q91A DSS1NB32A331Q92A	330 pF±10%				
	DSS1NB32A331Q93A DSS1NB32A471Q55B DSS1NB32A471Q91A DSS1NB32A471Q92A	470 pF±10%		100VDC		
	DSS1NB32A471Q93A DSS1NB32A681Q55B DSS1NB32A681Q91A DSS1NB32A681Q92A	680 pF±10%				
	DSS1NB32A681Q93A DSS1NB32A102Q55B DSS1NB32A102Q91A DSS1NB32A102Q92A	1000 pF±10%				
	DSS1NB32A102Q93A DSS1NB32A152Q55B DSS1NB32A152Q91A	1500 pF±10%				
	DSS1NB32A152Q92A DSS1NB32A152Q93A DSS1NB32A222Q55B DSS1NB32A222Q91A	2200 pF±10%				
	DSS1NB32A222Q92A DSS1NB32A222Q93A DSS1NB32A332Q55B DSS1NB32A332Q91A		-			
	DSS1NB32A332Q92A DSS1NB32A332Q93A DSS1NB32A472Q55B	3300 pF±10%	-			
	DSS1NB32A472Q91A DSS1NB32A472Q92A DSS1NB32A472Q93A	4700 pF±10%				

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Unit Mass Temperature Customer Withstanding Murata Rated Capacitance (Typical Characteristics Part Number Part Number Voltage Voltage value) DSS1NB32A682Q55B DSS1NB32A682Q91A 6800 pF±10% DSS1NB32A682Q92A DSS1NB32A682Q93A DSS1NB32A103Q55B DSS1NB32A103Q91A 10000 pF±10% DSS1NB32A103Q92A DSS1NB32A103Q93A 100VDC 250VDC DSS1NB32A153Q55B DSS1NB32A153Q91A 15000 pF±10% DSS1NB32A153Q92A DSS1NB32A153Q93A DSS1NB32A223Q55B DSS1NB32A223Q91A 22000 pF±10% ±10% 0.45g DSS1NB32A223Q92A DSS1NB32A223Q93A DSS1NB31H333Q55B DSS1NB31H333Q91A 33000 pF±10% DSS1NB31H333Q92A DSS1NB31H333Q93A DSS1NB31H473Q55B DSS1NB31H473Q91A 47000 pF±10% 50VDC 125VDC DSS1NB31H473Q92A DSS1NB31H473Q93A DSS1NB31H104Q55B DSS1NB31H104Q91A 100000pF±10% DSS1NB31H104Q92A DSS1NB31H104Q93A

4. Style and Dimension

See item 9.

5. Marking

Trade Mark : Marked as C1 Capacitance : Marked three digits system. (Ex.221) Rated Voltage : Marked voltage value.(100V)

6. Testing Conditions

<Unless otherwise specified>
 Temperature : Ordinary Temperature 15 to 35°C
 Humidity : Ordinary Humidity 25 to 85 %(RH)

<In case of doubt>
Perform a heat treatment at 150+0/-10°C for one hour
and then set at room temperature for 24±2 hours.
Temperature : 20 ± 2°C
Humidity : 60 to 70 %(RH)
Atmospheric Pressure : 86 to 106 kPa

7. Performance

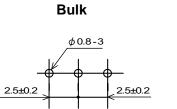
No.	Item	Specification	Test Method	
7.1	Appearance and Dimensions	Meet item 9.	Visual Inspection and measured with Slide Calipers.	
7.2	Marking	Marking is able to be read easily.	Visual Inspection.	
7.3	Capacitance and Tolerance	Meet item 3.	Table 2 Frequency Test Voltage Capacitance 1±0.1MHz 1±0.2Vrms 22pF~150pF 1±0.1kHz 1±0.2Vrms 220pF~100000pF	
7.4	Insulation Resistance(I.R.)	Meet item 3.	Test Voltage : Rated Voltage Time : 1 minute through a suitable resistor $1M\Omega$.	

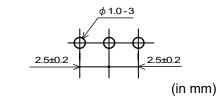
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No.	Item	Spe	cification	Test Method			
	Withstanding	Products shall not be damaged.		Test Voltage : 2.5 times for Rated Voltage			
	Voltage			Time : 1 to 5 seconds			
	0			Charge Current : 10 mA max.			
				It shall be applied between input / output terminal			
				and ground terminal.			
7.6	Temperature	Meet item 3.		Capacitance shall be measured at each step specified			
	Characteristics	-		in Table 3 after reaching the thermal equilibrium.			
				The capacitance change against the capacitance at			
				step 3 shall be calculated.			
				Table3			
				Step 1 2 3 4 5			
				Temp. +20±2 40±2 +20±2 +85±2 +20±2			
				(°C)			
7.7	Solderability	Along the circumfe	rence of terminal	Flux : Ethanol solution of rosin,25(wt)%			
	condendatinty	-	with new solder at le				
		75%.		Pre-heat : $150 \pm 10^{\circ}$ C, $60 \sim 90$ s			
				Solder : Sn-3.0Ag-0.5Cu			
				Solder Temperature 245±5°C			
				Immersion Time : 2 ± 0.5 seconds			
				Immersion Depth :			
				2 to 2.5 mm from the bottom of the body.			
7.8	Resistance to	Meet Table 4.		Flux : Ethanol solution of rosin,25(wt)%			
	Soldering Heat [®]	<u>Table 4</u>	1	(dipped for 5 to 10 seconds)			
		Appearance	No damaged.	Pre-heat : $150 \pm 10^{\circ}$ C, $60 \sim 90$ s			
		Capacitance	within ± 30%	Solder : Sn-3.0Ag-0.5Cu Solder Temperature : 270 ± 5 °C			
		Change	Within ± 50%	Immersion Time : 3± 0.5 seconds			
		Withstanding	No damaged.	Immersion Depth :			
		Voltage		1.6 ± 0.7 mm from the bottom of the body.			
				Then measured after exposure in the room			
				condition for 4 to 24hours.			
	Resistance to			Soldering iron output: 30W			
	Soldering Heat@			Tip temperature : 370±10°C			
				Soldering time : 5s(+0/-1s)			
7.9	Humidity	Meet Table 5.		Temperature : 60°C			
	,	Table 5		Humidity : 90 to 95 %(RH)			
				Time : 500 hours(+24-0 hours)			
			No damaged.	Then measured after exposure in the room			
		Capacitance	within ± 30%	condition for 4 to 24hours.			
7.10	Humidity Life	Change		– Temperature : 40 ± 2°C			
	,	Inslation		Humidity : 90 to 95 %(RH)			
		Resistance	10MΩ min.	Time : 500 hours(+24-0 hours)			
				Applying Voltage : 1H/ Rated Voltage 50VDC			
				2A/ Rated Voltage 100VDC			
				Then measured after exposure in the room			
				condition for 4 to 24hours.			
7.11	Heat Life			Temperature : 85 ± 3°C			
				Applying Voltage : 1H/ Rated Voltage 50VDC			
				2A/ Rated Voltage 100VDC			
				Time : 500 hours(+24-0 hours)			
				Then measured after exposure in the room			
				condition for 4 to 24hours.			

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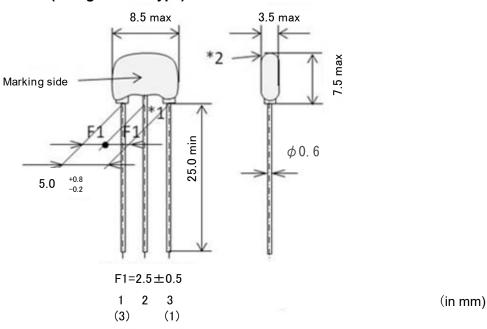
8. Mounting Hole





Taping

9. Style and Dimension 9.1 Bulk(Straight Lead Type) : Q55B



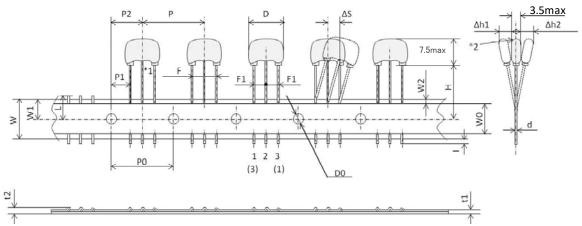
*1.Bottom of dielectric may be exposed.

*2. There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

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9.2 Taping(Straight Lead Type) : Q9 A

(All symbols in the illustrations below are described in Table 6)



*1.Bottom of dielectric may be exposed.

*2. There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

<u>Table 6</u>

Code	Description		Dimensions	Remark
Ρ	Pitch of Component		12.7	Product Inclination ∆S Determines Crossing
P0	Pitch of Sprocket Hole		12.7±0.2	
P1	Length from Hole Center to Lead		3.85±0.7	
P2	Length from Hole Center to Component Center		6.35±1.3	
D	Width of Body		8.5 max.	
ΔS	Deviation along tape, Left or Right		0±1.0	
W	Carrier Tape Width		18.0±0.5	
W1	Position of Sprocket Hole		9.0 +0,-0.5	Tape Widthwise Shift
Ι	Protrusion Length		+0.5 ~ -1.0	
D0	Diameter of Sprocket Hole		φ 4.0±0.1	
d	Lead Diameter		φ 0.6	
t1	Total Tape Thickness		0.7±0.2	Includes Thickness of
t2	Total Thickness, Tape and Lead Wire		1.5 max.	Bonding Tape
∆h1	Deviation across Tape,front		1.0 max.	
Δ h2	Deviation across Tape,rear		1.0 max.	
L	Portion to Cut in Case of Defect		11.0 +0,-1.0	
Wo	Hold Down Tape Width		12.0±0.5	
W2	Hold Down Tape Position		1.5±1.5	
Н		Q91	20.0±1.0	
	Lead length between sprocket	Q92	16.5±1.0	
	hole and forming position	Q93	18.5±1.0	
F	Land Creating		5.0 +0.8,-0.2	
F1	Lead Spacing		2.5 +0.4,-0.2	

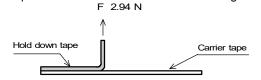
(in mm)

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10. Taping

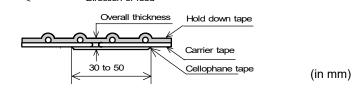
- (1) A maximum of 0.3% of the components quantity per Ammo pack may be missing without consecutive missing components.
- (2) The adhesive power of the tape shall have over 2.94N at the following condition.



(3) Splicing method of tape

1. Carrier tape

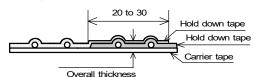
Carrier tape shall be spliced by cellophane tape. Overall thickness shall be less than 1.05 mm.



2. Hold down tape

Hold down tape shall be spliced with overlapping.

Overall thickness shall be less than 1.05 mm.



3. Both carrier tape and hold down tape

Both tapes shall be cut zigzag and spliced with splicing tape.

11. Packing

11.1 Packing quantity

The standard packing quantity is as follows.

(The packing quantity may be changed due to a fraction of order.)

Minimun Packing Form and Quantity

Terminal Configuration	A Unit Quantity	Packing Form	* Standard Quantity in a container (corrugated cardboard box)
Bulk	250 pcs.	In a plastic bag	5000pcs.
Taping	1500 pcs.	In an Ammo pack	7500pcs.

* A quantity in a container is depending on a quantity of an order.

11.2 Packing Form

(1) Bulk

<A plastic bag pack>

1.Products are packed into a plastic bag.

- a plastic bag
- 2. The plastic bags are put into a container (corrugated cardboard box) depending on a quantity of an order.

(in mm)

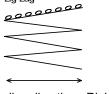
the plastic bag with products - a container

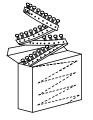
container label

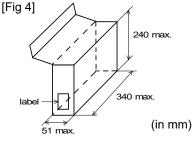
quantity the

- (2) Taping
- <An ammo pack>
- 1 .Folding the tape per 25 pitches, products are packed into an ammo package so that each product of each layer wound zigzag is put on top of one another. [Fig 3]
- 2. The dimensions of the ammo package are indicated in [Fig 4].
- 3. The ammo packages are put into a container (corrugated cardboard box) depending on a quantity of an order.
- 4. Not less than 3 consecutive of component shall be missing on both edge of tape.

[Fig 3] _{zig zag}







The unloading direction : Right

The hold down tape : Upper

The product body : Left along the unloading direction

12. Marking on package

12.1 Unit Package

Bulk : Marked on a plastic bag. Taping : Marked on a label stuck on an ammo package.

Marking on a unit package consists of : Customer part number, MURATA part number, Inspection number(*1), RoHS marking (*2), Quantity, etc

*1) « Expression of Inspection	on No. » $\frac{\Box}{(1)} \xrightarrow{OOOO} \frac{\times \times}{(3)}$
(1) Factory Code (2) Date	First digit : Year / Last digit of year Second digit : Month / Jan. to Sep. \rightarrow 1 to 9, Oct. to Dec. \rightarrow O,N,D
(3) Serial No.	Third, Fourth digit : Day

*2) « Expression of RoHS marking » ROHS – <u>Y</u> (<u>(</u>)

(1) RoHS regulation conformity parts.

(2) MURATA classification number

12.2 Container

Marking on the label stuck on a container consists of : Customer name Purchasing Order Number, Customer Part Number, MURATA part number, RoHS marking (*2), Quantity, etc

13. 🛆 Caution

13.1 Mounting holes

Mounting holes should be designed as specified in this specifications. Or different design from this specifications may cause cracks in ceramics which may lead to smoking / firing.

13.2 Caution for the product angle adjust work

Take care not to apply any mechanical stress to product body at the lead terminal bending process for product angle adjustment after insertion.

13.3 Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
 - (7) Traffic signal equipment
- (2) Aerospace equipment (7) Disaster prevention / crime prevention equipment
- (3) Undersea equipment
- (9) Data-processing equipment
- (4) Power plant control equipment (10) Applications of similar complexity and /or reliability requirements to the applications listed in the above
- (5) Medical equipment (6) Transportation equipment (vehicles, trains, ships, etc.)
 - MURATA MFG.CO., LTD

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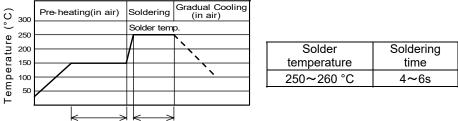
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14. Notice

14.1 Soldering

- (1) Use rosin-based flux. Do not use strong acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
 - Use Sn-3.0Ag-0.5Cu solder

(2) Standard flow soldering profile.



1 minutes min. Soldering time

- (3) Resistance to soldering iron goes in the following condition that tip temperature is 350 °C max. And soldering time is 5 s max.
- (4) Products and the leads should not be subjected to any mechanical stress during soldering process. (and also while subjected to the equivalent high temperature.)

14.2 Cleaning

- Products shall be cleaned on following conditions.
- (1) Cleaning Temperature: 60°C max.(40°C max. for Isopropyl alcohol).
- (2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.

Power : 20W / I max.

 $Frequency\,:\,28kHz\sim40kHz$

Time : 5 minutes max.

- (3) Cleaning agent
 - 1. alcohol cleaning agents.
 - Isopropyl alcohol (IPA)
 - 2. Aqueous cleaning agent
 - Pine Alpha ST-100S
- (4) Ensure that residual flux and residual cleaning agent is completely removed.
- Products should be thoroughly dried after aqueous agent has been removed with de-ionized water.
- (5) For other cleaning methods, please contact Murata engineering.

14.3 Operating Environment

- (1) Do not use products in corrosive gases such as chlorine gas, acid or sulfide gas.
- (2) Do not use products in the environment where water, oil or organic solvents may adhere to products.
- (3) Do not adhere any resin to products, coat nor mold products with any resin (including adhesive)to prevent mechanical and chemical stress on products.

14.4 Storage and handling requirements.

- (1) Storage period
 - Use the products within 12 months after delivered.
 - Solderability should be checked if this period is exceeded.
- (2) Storage environment condition
 - To prevent products quality deterioration, stored conditions should be controlled as follows ;
 - 1. Temperature : -10 to 40 degrees centigrade
 - 2. Humidity : 15 to 85% relative humidity
 - 3. Products should be stored without sudden changes in temperature and humidity.
 - Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of lead terminals resulting in poor solderability.
 - 4. Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.

5. Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on. (3) Handling Conditions

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

15. **A**Note

- (1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2)You are requested not to use our product deviating from the reference specifications.
- (3)The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.

MURATA MFG.CO., LTD